

S. Patent Feb. 11, 2003 Sheet 2 of 3 US 6,518

FIG. 2

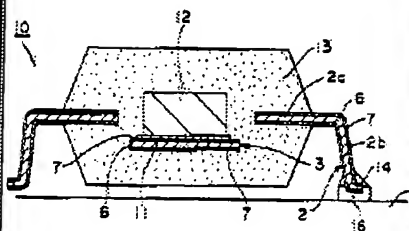
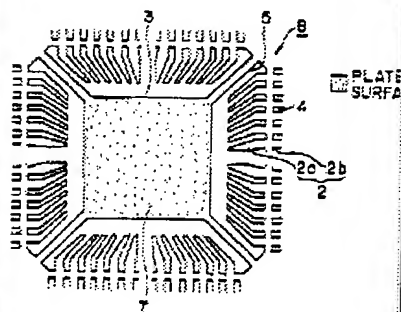


FIG. 3



US-PAT-NO: 6518653

DOCUMENT-IDENTIFIER: US 6518653 B1

TITLE: Lead frame and semiconductor device

DATE-ISSUED: February 11, 2003

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APPL-NO: 09/ 328260

DATE FILED: June 10, 1999

FOREIGN-APPL-PRIORITY-DATA:

COUNTRY	APPL-NO	APPL-DATE
JP	10-166441	June 15, 1998

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Title

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